PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: ERIC J. BERGMAN

EXAMINER:

APPLICATION No.:

NOT YET ASSIGNED

ART UNIT:

FILED:

OCTOBER 7, 2003

CONF. NO:

SURFACES

FOR: METHODS FOR CLEANING SEMICONDUCTOR

INFORMATION DISCLOSURE STATEMENT

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

1. Timing of Submission

This information disclosure statement is being filed concurrently with the filing of the application. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

2. Cited Information

Copies of the foreign references and literature can be found in parent U.S. Application Serial No. 09/811,925.

3. Effect of Information Disclosure Statement (37 C.F.R. § 1.97(h))

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols,

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as "Express Mail Post Office to Addressee" in an envelope addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Express Mail Label No.: EV 254990096US Name of Person Mailing Paper: Debbje Gilbert

Date of Deposit: October 7, 2003 Signature of Person Mailing Paper:

results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

4. Fee Payment

No fees are believed due because this Information Disclosure Statement is being filed concurrently with the filing of the application.

Respectfully submitted,

Perkins Coie LLP

Date: Oct. 6, 2003

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EM No. EV 254990096US **COMPLETE IF KNOWN** Application Number Not yet assigned INFORMATION DISCLOSURE Confirmation Number STATEMENT BY APPLICANT Filing Date October 7, 2003 Form PTO-1449 (Modified) First Named Inventor Eric J. BERGMAN (Use several sheets if necessary) Group Art Unit **Examiner Name** Sheet 1 of 5 Attorney Docket No. 54008.8012.US04

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| • • | | Filing Date | October 7, 2003 | | | |
| | | • | | First Named Inventor | Eric J. BERGMAN | |
| | (Use several she | eets if necessary | ') | Group Art Unit | | |
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EM No. EV 254990096US INFORMATION DISCLOSURE STATEMENT BY APPLICANT Form PTO-1449 (Modified) (Use several sheets if necessary) COMPLETE IF KNOWN Application Number Confirmation Number Filing Date October 7, 2003 First Named Inventor Group Art Unit Examiner Name

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EM No. EV 254990096US **COMPLETE IF KNOWN** Application Number Not yet assigned INFORMATION DISCLOSURE Confirmation Number STATEMENT BY APPLICANT Filing Date October 7, 2003 Form PTO-1449 (Modified) First Named Inventor Eric J. BERGMAN (Use several sheets if necessary) Group Art Unit Examiner Name Sheet 4 of 5 Attorney Docket No. 54008.8012.US04

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| | | | | Application Number | Not yet assigned | |
| | INFORMATION | | | Confirmation Number | | |
| • | STATEMENT B | | | Filing Date | October 7, 2003 | |
| | Form PTO-14 | • | | First Named Inventor | Eric J. BERGMAN | |
| | (Use several she | ets if necessary) |) | Group Art Unit | | |
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| Sheet | 5 | of | 5 | Attorney Docket No. | 54008.8012.US04 | |

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